

DATA SHEET

PCF8801 LCD driver for 140 × 2 segments

Product specification
File under Integrated Circuits, IC12

2000 Feb 04

LCD driver for 140 × 2 segments**PCF8801****FEATURES**

- Single-chip LCD controller/driver
- Fixed backplane multiplexing at a rate of 1 : 2
- Internal LCD bias generation ($0.5V_{DD}$)
- 140 segment outputs configured to drive seven 40-segment characters
- On-chip oscillator with one external resistor
- Wide power supply range (2.7 V up to 5.5 V)
- Low power consumption
- Compatible with most microprocessors/microcontrollers
- 1 MHz serial bus interface (280-bit shift register)
- Easily cascaded for large LCD applications (two cascade directions possible)
- Compatible with chip-on-glass technology
- Manufactured by silicon gate CMOS process.

The chip can easily be cascaded for larger LCD applications, and the direction of the information flow in the cascade can be selected. The PCF8801 is compatible with most microprocessors/microcontrollers and communicates via a serial bus interface comprising a 280-bit shift register.

The outputs are multiplexed by a clock signal generated by the internal oscillator which needs only one external resistor. Cascade applications only require the clock signal to be generated by the first device with the internal oscillators in the other devices disabled.

The PCF8801 is designed for chip-on-glass applications. It has a narrow package with raised points (bumps) for easy assembly on to LCD glass.

GENERAL DESCRIPTION

The PCF8801 is a peripheral device which interfaces a multiplexed Liquid Crystal Display (LCD) having two backplanes and up to 140 segments. It generates drive signals at a multiplex rate of 1 : 2 allowing seven 40-segment (5 x 8) characters to be driven.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PCF8801U	–	chip with bumps in tray	–

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BLOCK DIAGRAM

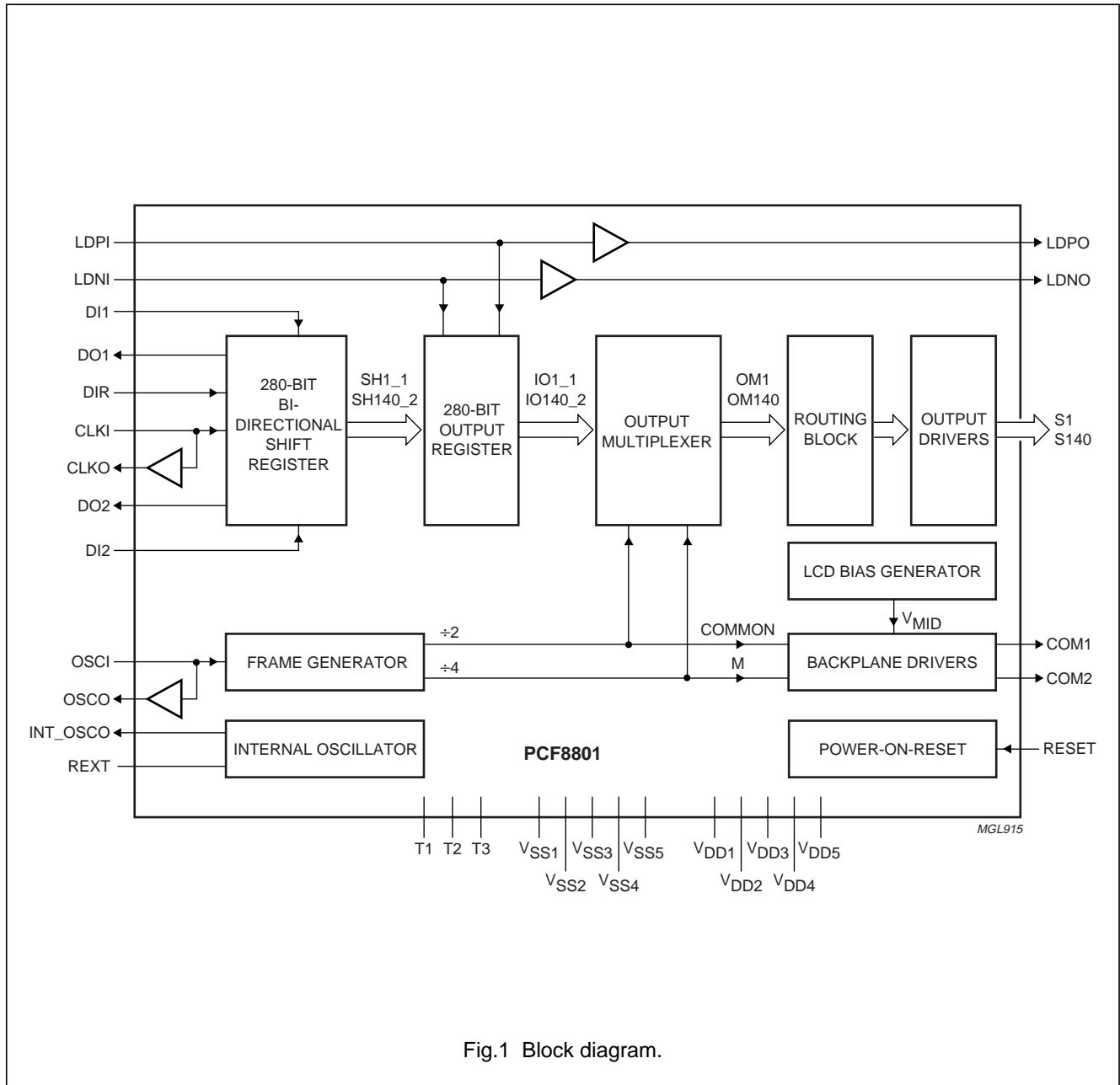


Fig.1 Block diagram.

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PINNING

SYMBOL	PAD	SIMPLIFIED SYMBOL ⁽¹⁾	DESCRIPTION
V _{DD1} to V _{DD4}	28, 27, 3, 4	V _{DD}	Power supply for output drivers, backplane drivers and LCD bias generator; 4 pads connected internally
V _{SS1} to V _{SS4}	30, 29, 1, 2	V _{SS}	Ground for output drivers, backplane drivers and LCD bias generator; 4 pads connected internally
V _{DD5}	16	V _{DD}	Power supply for remaining circuitry; connect externally to V _{DD1} to V _{DD4}
V _{SS5}	15	V _{SS}	Ground for remaining circuitry; connect externally to V _{SS1} to V _{SS4}
REXT	10		Enable internal oscillator input; connected via an external resistor
RESET	14		Reset input; active HIGH
T1 to T3	13, 17, 18		Test pads; must remain unconnected
COM1_1, COM1_2	31, 173	COM1	First pair of identical 3-level LCD backplane outputs; each pad is located on opposite sides of the die
COM2_1, COM2_2	32, 174	COM2	Second pair of identical 3-level LCD backplane outputs; each pad is located on opposite sides of the die
DIR	19		Data direction control input; its voltage level determines the direction in which data is shifted
S1 to S140	33 to 172		LCD driver outputs
DI1, DI2	24, 7	DI	Data input; the status of DIR determines which pad is valid; each pad is located on opposite sides of the die
DO1, DO2	23, 8	DO	Data outputs; both identical; both always valid; for cascade use; each pad is located on opposite sides of the die
LDP1, LDP2	26, 5	LDPI, LDPO	Data load control input (LDPI) and output (LDPO) on rising edge; the status of DIR determines which pad is valid; each pad is located on opposite sides of the die
LDN1, LDN2	25, 6	LDNI, LDNO	Data load control input (LDNI) and output (LDNO) on falling edge; the status of DIR determines which pad is valid; each pad is located on opposite sides of the die
CLK1, CLK2	22, 9	CLKI, CLKO	Data shift clock input (CLKI) and output (CLKO); the status of DIR determines which pad is valid; for cascade use; each pad is located on opposite sides of the die
OSC1, OSC2	21, 11	OSCI, OSCO	LCD multiplexing clock input (OSCI) and output (OSCO); the status of DIR determines which pad is valid; each pad is located on opposite sides of the die
INT_OSCO1, INT_OSCO2	20, 12	INT_OSCO	Internal oscillator outputs; both identical; each pad is located on opposite sides of the die

Note

1. These symbols simplify descriptions in this data sheet where several pads have the same function and also indicate the direction of data on pads which can be selected to be either an input or an output.

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FUNCTIONAL DESCRIPTION

Refer to block diagram Fig.1. The PCF8801 comprises a bi-directional 280-bit input shift register, 280-bit output register, output multiplexer providing 140-segment outputs via a routing block and output drivers, two 3-level backplane outputs, internal oscillator and internal power-on reset circuit. To reduce the length of routing required between cascaded chips in multiple chip-on-glass applications, all inputs/outputs for control lines, clock signals and data are provided at both sides of the narrow package.

Shift register

The 280-bit bi-directional shift register shifts data on the rising edge of clock signal CLKI. The shift register output bits are called SH1_1, SH1_2 to SH140_1, SH140_2. The direction in which data is shifted and the pads that are valid for inputs DI, CLKI and output CLKO, is determined by the voltage level on pad DIR. The voltage on pad DIR must be tied to either V_{DD} or V_{SS} and must not be switched when the PCF8801 is operating. The relationship between the status of pad DIR and the other pads connected to the shift register is shown in Table 1.

Table 1 280-bit bi-directional shift register pads

SHIFT DIRECTION	VALID PAD	
	DIR = 1	DIR = 0
Data input DI ⁽¹⁾	DI1	DI2
Data output DO ⁽²⁾	DO1 and DO2	DO1 and DO2
Clock input CLKI	CLK1	CLK2
Clock output CLKO ⁽²⁾	CLK2	CLK1
First bit shifted	SH140_2	SH1_1
Last bit shifted ⁽³⁾	SH1_1	SH140_2

Notes

1. The invalid DI pad must be connected to either V_{DD} or V_{SS}.
2. Pads DO and CLKO are used when PCF8801 devices are connected in cascade.
3. The last bit is loaded into a flip-flop whose output is connected to pad DO. The value of the last bit appears at pad DO delayed by a 1/2 CLKI period.

Output register

The 280-data bits (SH1_1, SH1_2 to SH140_1, SH140_2) from the output of the shift register are transferred to the input of the 280 bit output register. Data is transferred when either pad LDPI goes HIGH or when pad LDNI goes LOW. The output register bits are called IO1_1, IO1_2 to IO140_1, IO140_2. The pads that are valid for inputs LDPI, LDNI, OSCI, and outputs LDPO, LDNO, OSCO are determined by the voltage level on pad DIR. During a positive pulse on pad LDPI, pad LDNI must stay HIGH, or during a negative pulse on pad LDNI, pad LDPI must stay LOW. The voltage on pad DIR must be tied to either V_{DD} or V_{SS} and must not be switched when the PCF8801 is operating. The relationship between the status of pad DIR and the other pads connected to the output register is shown in Table 2.

Table 2 280-bit output register pads

SHIFT DIRECTION	VALID PAD	
	DIR = 1	DIR = 0
Data load input LDPI	LDP1	LDP2
Data load output LDPO	LDP2	LDP1
Data load input LDNI	LDN1	LDN2
Data load output LDNO	LDN2	LDN1
Multiplexing clock input OSCI	OSC1	OSC2
Multiplexing clock output OSCO	OSC2	OSC1

Output multiplexer, frame generator and backplane drivers

The 280 data bits (IO1_1, IO1_2 to IO140_1, IO140_2) from the output register are transferred to the input of the output multiplexer which multiplexes the data at the rate of 1 : 2. The 140 output bits from the output multiplexer are called OM1 to OM140. The frame generator outputs two control signals derived from the LCD multiplex clock (OSCI) called COMMON (1/2 f_{OSC}) and M (1/4 f_{OSC}) which control the output multiplexer and the backplane drivers. The operation of the output multiplexer is defined in Table 3.

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Table 3 Output multiplexer truth table
n = 1 to 140; X = don't care.

CONTROL INPUT		DATA INPUT		DATA OUTPUT
COMMON	M	IOn_1	IOn_2	OMn
0	0	0	X	0
0	0	1	X	1
1	0	X	0	0
1	0	X	1	1
0	1	0	X	1
0	1	1	X	0
1	1	X	0	1
1	1	X	1	0

The backplane drivers generate two output signals called COM1 and COM2 which connect directly to LCD backplane 1 and to backplane 2 respectively. These signals have 3 voltage levels called V_{DD}, V_{MID} and V_{SS}, where V_{SS} = 0 V and V_{MID} = 1/2V_{DD}. V_{MID} is the LCD bias voltage generated by the LCD bias generator. Figure 2 is a timing diagram for the output multiplexer, frame generator and backplane drivers.

Routing block and output drivers

The layout of the LCD interconnection requires each of the 140 outputs (OM1 to OM140) from the output multiplexer to be mapped to the corresponding pixel in each LCD character by the routing block. The outputs of the routing block are fed to output drivers whose outputs are pads S1 to S140. Table 4 shows which pixel is driven by which data bit output by the shift register for the first LCD character. There are 7 characters in total, each character has 40 data points, so routing is performed on a point-by-point basis.

A pixel has 2 segments which are activated by backplane drive signals COM1 and COM2 respectively. If DIR = 0, the first data bit of the data stream to be loaded into the shift register is routed to the first pixel. Data bit SH1_1 is routed to pixel 1, activated by COM1, and data bit SH1_2 is routed to pixel 1, activated by COM2.

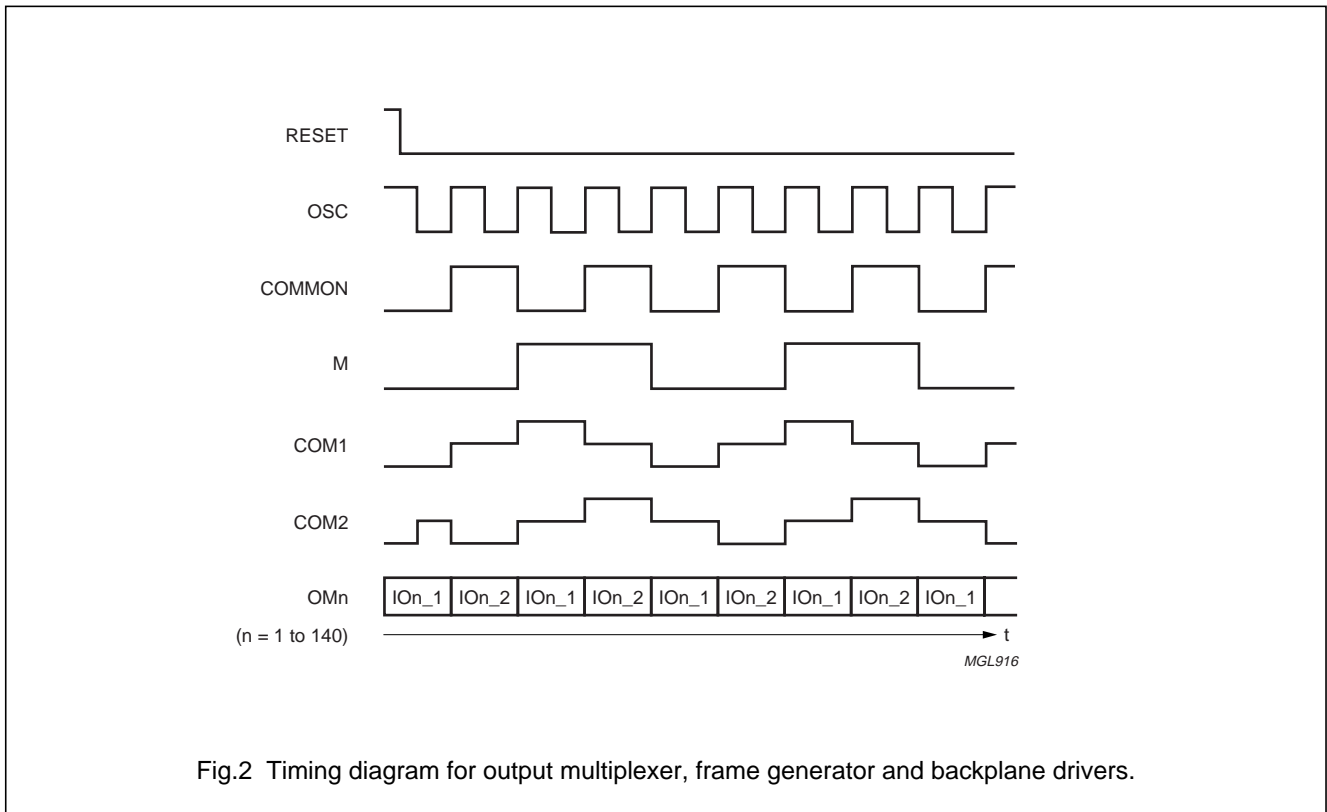


Fig.2 Timing diagram for output multiplexer, frame generator and backplane drivers.

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Table 4 Routing of data to LCD pixels
(First 20 bits, DIR = 0).

SHIFT REGISTER DATA OUTPUT	LCD PIXEL
SH1_1	7
SH1_2	
SH2_1	5
SH2_2	
SH3_1	3
SH3_2	
SH4_1	1
SH4_2	
SH5_1	9
SH5_2	
SH6_1	6
SH6_2	
SH7_1	4
SH7_2	
SH8_1	2
SH8_2	
SH9_1	11
SH9_2	
SH10_1	10
SH10_2	
SH11_1	8
SH11_2	

SHIFT REGISTER DATA OUTPUT	LCD PIXEL
SH12_1	12
SH12_2	
SH13_1	13
SH13_2	
SH14_1	14
SH14_2	
SH15_1	17
SH15_2	
SH16_1	19
SH16_2	
SH17_1	15
SH17_2	
SH18_1	16
SH18_2	
SH19_1	18
SH19_2	
SH20_1	20
SH20_2	

The PCF8801 supports a 5 × 8 LCD character structure as shown in Fig.3. Because the bottom line of pixels are not often used in most applications, their data could be used instead to control LCD icons.

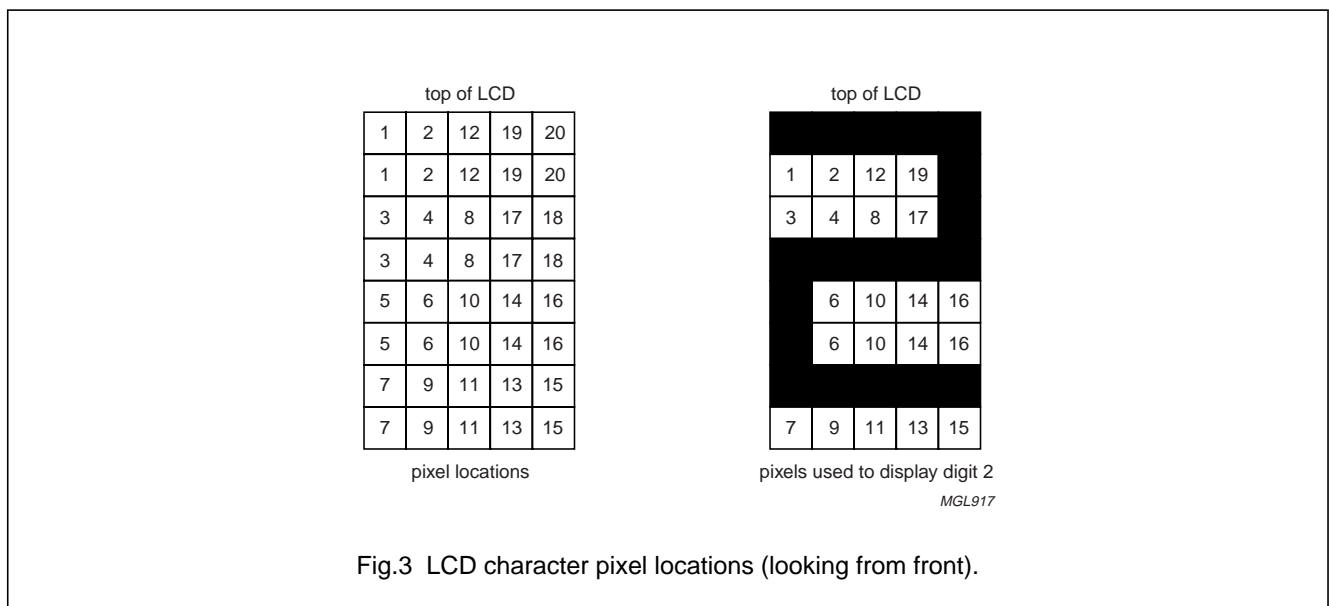


Fig.3 LCD character pixel locations (looking from front).

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Internal oscillator

The internal oscillator generates two identical LCD multiplexing clock signals (INT_OSCO) having a minimum frequency of 240 Hz at pads INT_OSCO1 and INT_OSCO2. The internal oscillator is enabled by connecting an external resistor between pad REXT and V_{DD}, and disabled (INT_OSCO = 0) by connecting pad REXT to V_{SS}. An external resistor value of 330 kΩ will typically generate a frequency of 500 Hz.

For cascade applications, the first chip in the cascade should have pad INT_OSCO connected to pad OSCI. Each OSCI pad of all subsequent chips should be connected to the OSCO pad of the previous chip (see Fig.4). The signal applied to the OSCI pad must always be a clock signal; applying a DC signal could damage the LCD.

Power-on reset and external reset

At power-on, the PCF8801 resets to the following conditions:

- The shift register and the output register sets all bits to 0
- The frame generator outputs (COMMON and M) are 0
- The multiplexed outputs (S1 to S140) to the LCD pixels are 0
- The backplane driver outputs (COM1 and COM2) are 0 until the first falling edge of OSCI (see Fig.2).

A positive pulse on pad RESET (active HIGH) has the same effect as the power-on reset. A HIGH-level on pad RESET disables all clock inputs, the bias generator, and the internal oscillator (INT_OSCO = 0). If the RESET input is not used, it is advisable to connect its pad directly to the adjacent pad V_{SS5}. However, if the RESET input is to be used in a chip-on-glass application, it is strongly advised that the RESET input is connected in series with an on-glass resistance to reduce its sensitivity to ESD/EMC disturbances. The minimum value of resistance recommended by the ITO is 8 kΩ.

Cascading

To reduce the length of routing required between cascaded chips on-glass, all inputs/outputs for control lines, clock signals and data are provided at both sides of the narrow package. An example of cascading is shown in Fig.4.

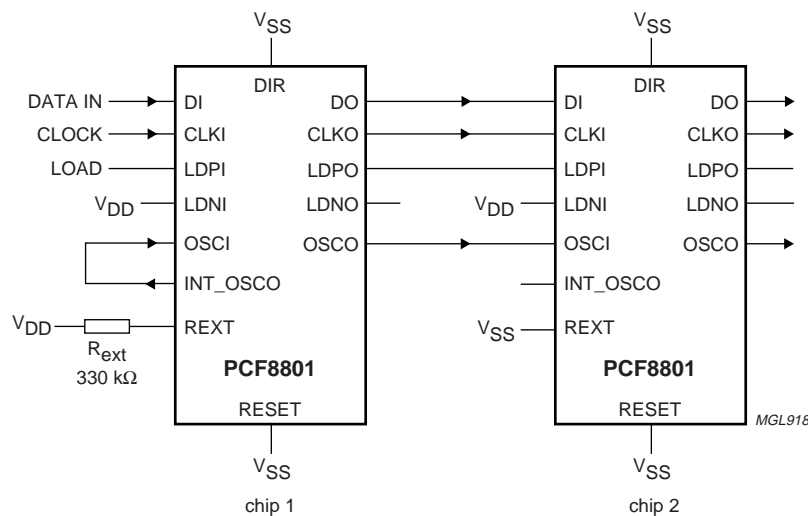


Fig.4 Example of cascading.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134); stresses greater than the values shown may cause permanent damage to the device; parameters are valid over the ambient temperature range; all voltages are with respect to V_{SS} .

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{DD}	supply voltage	-0.5	+6.5	V
V_I	input voltage	$V_{SS} - 0.5$	$V_{DD} + 0.5$	V
V_O	output voltage	$V_{SS} - 0.5$	$V_{DD} + 0.5$	V
I_I	DC input current	-10	+10	mA
I_O	DC output current	-10	+10	mA
I_{DD}	V_{DD} current	-50	+50	mA
I_{SS}	V_{SS} current	-50	+50	mA
P_{tot}	total power dissipation	-	500	mW
P_{out}	power dissipation per output	-	10	mW
T_{amb}	ambient temperature	-40	+85	°C
T_{stg}	storage temperature	-65	+150	°C

HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However it is good practice to take normal precautions appropriate to handling MOS devices (see "Handling MOS devices").

DC CHARACTERISTICS

$V_{DD} = 2.7$ to 5.5 V; $V_{SS} = 0$ V; $T_{amb} = -40$ to $+85$ °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V_{DD}	supply voltage		2.7	3 or 5	5.5	V
I_q	quiescent supply current	RESET = 1; note 1	-	2.5	10	μA
I_{DD3}	normal mode supply current	CLKI = 0; OSCI = INT_OSCO; note 1	-	32	100	μA
Logic						
V_{IL}	LOW-level input voltage	note 2	V_{SS}	$0.33V_{DD}$	$0.2V_{DD}$	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	$0.37V_{DD}$	V_{DD}	V
I_{OL}	LOW-level output current	$V_{OL} = 0.4$ V; $V_{DD} = 5$ V	1	3	-	mA
I_{OH}	HIGH-level output current	$V_{OH} = 4.6$ V; $V_{DD} = 5$ V	-	-3	-1	mA
I_{LI}	input leakage current	$V_I = V_{DD}$ or V_{SS}	-1	0	+1	μA
V_{POR}	Power-on reset voltage	$V_{DD} < V_{POR}$	0.8	1.2	1.6	V
C_i	input capacitance		-	-	15	pF
C_o	output capacitance		-	-	15	pF

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Outputs to LCD						
$V_{\text{COM(tol)}}$	output voltage tolerance on pad COM1 and pad COM2		-135	-10 to +10	+135	mV
$R_{\text{o(COM)}}$	output resistance on pad COM1 and pad COM2	$V_{\text{DD}} = 5 \text{ V}$; note 3	-	5	30	$\text{k}\Omega$
$R_{\text{o(S)}}$	output resistance on pads S0 to S140		-	7	30	$\text{k}\Omega$

Notes

- Outputs to LCD are unloaded (open-circuit); inputs are at V_{SS} or V_{DD} ; $R_{\text{ext}} = 330 \text{ k}\Omega$.
- All Schmitt trigger inputs.
- Measured one at a time; load current $30 \mu\text{A}$.

AC CHARACTERISTICS

$V_{\text{DD}} = 2.7$ to 5.5 V ; $V_{\text{SS}} = 0 \text{ V}$; $T_{\text{amb}} = -40$ to $+85 \text{ }^\circ\text{C}$; unless otherwise specified; all timing parameter values are valid within V_{DD} and T_{amb} range, and are referenced to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DD} . The serial interface timing parameters are defined in Fig.5.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R_{ext}	external resistor		264	330	396	$\text{k}\Omega$
f_{osc}	oscillator frequency at pad INT_OSCO and pad OSC1	note 1	240	500	1000	Hz
$t_{\text{H(OSC)}}$	HIGH time on pad OSC1		400	-	-	ns
$t_{\text{L(OSC)}}$	LOW time on pad OSC1		400	-	-	ns
$f_{\text{clk(CLK)}}$	data shift clock frequency on pad CLK1		-	-	1000	kHz
$t_{\text{H(CLK)(LD)}}$	HIGH time on pads CLK1, LDPI and LDNI		400	-	-	ns
$t_{\text{L(CLK)(LD)}}$	LOW time on pads CLK1, LDPI and LDNI		400	-	-	ns
$t_{\text{su(DI-CLK)}}$	set-up time DI to CLK1		50	-	-	ns
$t_{\text{h(D)}}$	data input hold time	DI stable after CLK1 rise	500	-	-	ns
t_{sep}	separation time between active edges of CLK1, LDPI and LDNI		800	-	-	ns

Note

- Frequency accuracy is valid within V_{DD} , T_{amb} and R_{ext} . Typical output duty cycle is 50 : 50.

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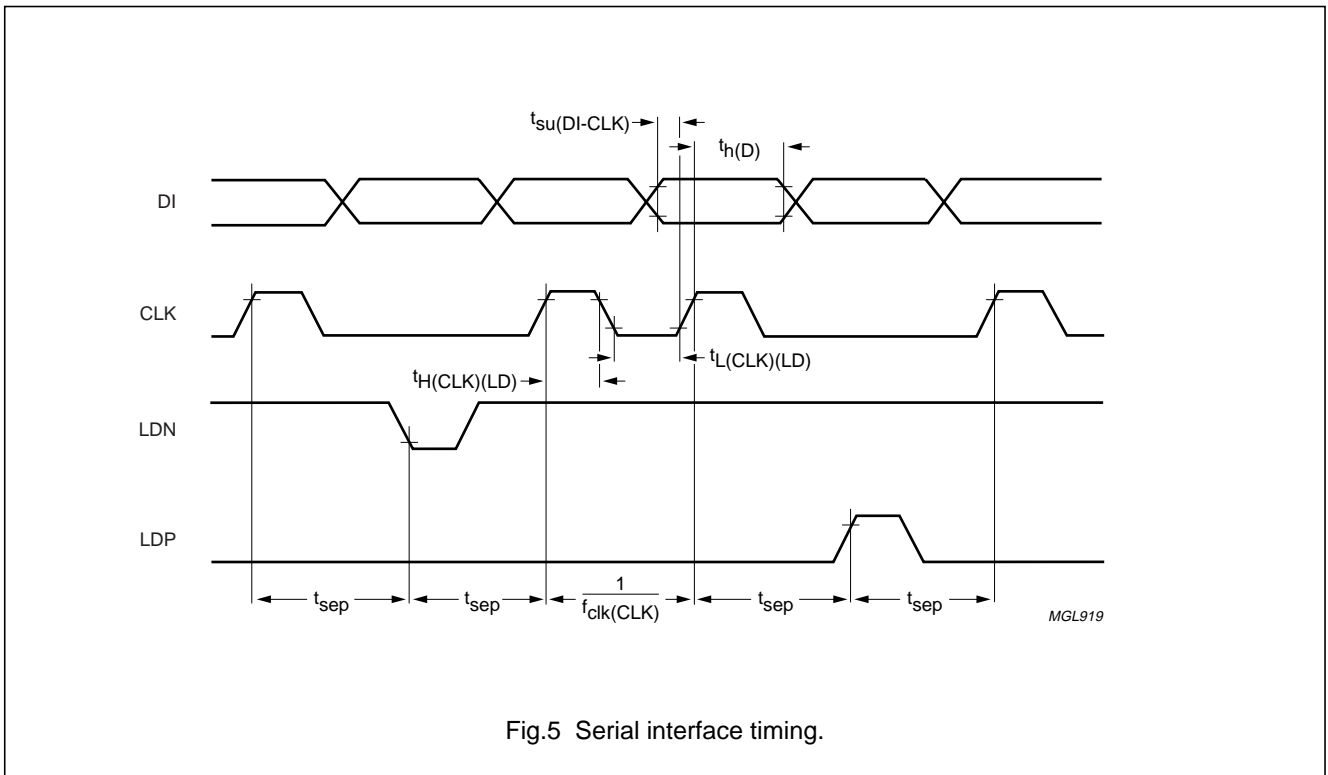


Fig.5 Serial interface timing.

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BONDING PAD INFORMATION

The PCF8801 is manufactured using n-well CMOS technology.

Table 5 Bonding pad locations

All x/y coordinates represent the position of the centre of each pad (in μm) with respect to the centre ($x/y = 0$) of the chip (see Fig.6).

SYMBOL	PAD	COORDINATES	
		x	y
V _{SS3}	1	-5644.4	382.4
V _{SS4}	2	-5644.4	307.4
V _{DD3}	3	-5644.4	232.4
V _{DD4}	4	-5644.4	157.4
LDP2	5	-5644.4	82.4
LDN2	6	-5644.4	-15.0
DI2	7	-5644.4	-115.0
DO2	8	-5644.4	-215.0
CLK2	9	-5644.4	-315.0
REXT	10	-5238.3	-439.4
OSC2	11	-5138.3	-439.4
INT_OSC02	12	-5038.3	-439.4
T1	13	-4913.3	-439.4
RESET	14	-134.6	-439.4
V _{SS5}	15	-47.1	-439.4
V _{DD5}	16	53.4	-439.4
T2	17	4791.2	-439.4
T3	18	4916.2	-439.4
DIR	19	5041.2	-439.4
INT_OSC01	20	5141.2	-439.4
OSC1	21	5241.2	-439.4
CLK1	22	5644.4	-314.9
DO1	23	5644.4	-214.9
DI1	24	5644.4	-114.9
LDN1	25	5644.4	-14.9
LDP1	26	5644.4	83.4
V _{DD2}	27	5644.4	158.4
V _{DD1}	28	5644.4	233.4
V _{SS2}	29	5644.4	308.4
V _{SS1}	30	5644.4	383.4
COM1_1	31	5401.7	440.0
COM2_1	32	5326.7	440.0

SYMBOL	PAD	COORDINATES	
		x	y
S1	33	5251.7	440.0
S2	34	5176.7	440.0
S3	35	5101.7	440.0
S4	36	5026.7	440.0
S5	37	4951.7	440.0
S6	38	4876.7	440.0
S7	39	4801.7	440.0
S8	40	4726.7	440.0
S9	41	4651.7	440.0
S10	42	4576.7	440.0
S11	43	4501.7	440.0
S12	44	4426.7	440.0
S13	45	4351.7	440.0
S14	46	4276.7	440.0
S15	47	4201.7	440.0
S16	48	4126.7	440.0
S17	49	4051.7	440.0
S18	50	3976.7	440.0
S19	51	3901.7	440.0
S20	52	3826.7	440.0
S21	53	3751.7	440.0
S22	54	3676.7	440.0
S23	55	3601.7	440.0
S24	56	3526.7	440.0
S25	57	3451.7	440.0
S26	58	3376.7	440.0
S27	59	3301.7	440.0
S28	60	3226.7	440.0
S29	61	3151.7	440.0
S30	62	3076.7	440.0
S31	63	3001.7	440.0
S32	64	2926.7	440.0
S33	65	2851.7	440.0
S34	66	2776.7	440.0
S35	67	2701.7	440.0
S36	68	2626.7	440.0
S37	69	2551.7	440.0
S38	70	2476.7	440.0
S39	71	2401.7	440.0

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SYMBOL	PAD	COORDINATES	
		x	y
S40	72	2326.7	440.0
S41	73	2251.7	440.0
S42	74	2176.7	440.0
S43	75	2101.7	440.0
S44	76	2026.7	440.0
S45	77	1951.7	440.0
S46	78	1876.7	440.0
S47	79	1801.7	440.0
S48	80	1726.7	440.0
S49	81	1651.7	440.0
S50	82	1576.7	440.0
S51	83	1501.7	440.0
S52	84	1426.7	440.0
S53	85	1351.7	440.0
S54	86	1276.7	440.0
S55	87	1201.7	440.0
S56	88	1126.7	440.0
S57	89	1051.7	440.0
S58	90	976.7	440.0
S59	91	901.7	440.0
S60	92	826.7	440.0
S61	93	751.7	440.0
S62	94	676.7	440.0
S63	95	601.7	440.0
S64	96	526.7	440.0
S65	97	451.7	440.0
S66	98	376.7	440.0
S67	99	301.7	440.0
S68	100	226.7	440.0
S69	101	151.7	440.0
S70	102	76.7	440.0
S71	103	-73.3	440.0
S72	104	-148.3	440.0
S73	105	-223.3	440.0
S74	106	-298.3	440.0
S75	107	-373.3	440.0
S76	108	-448.3	440.0
S77	109	-523.3	440.0
S78	110	-598.3	440.0

SYMBOL	PAD	COORDINATES	
		x	y
S79	111	-673.3	440.0
S80	112	-748.3	440.0
S81	113	-823.3	440.0
S82	114	-898.3	440.0
S83	115	-973.3	440.0
S84	116	-1048.3	440.0
S85	117	-1123.3	440.0
S86	118	-1198.3	440.0
S87	119	-1273.3	440.0
S88	120	-1348.3	440.0
S89	121	-1423.3	440.0
S90	122	-1498.3	440.0
S91	123	-1573.3	440.0
S92	124	-1648.3	440.0
S93	125	-1723.3	440.0
S94	126	-1798.3	440.0
S95	127	-1873.3	440.0
S96	128	-1948.3	440.0
S97	129	-2023.3	440.0
S98	130	-2098.3	440.0
S99	131	-2173.3	440.0
S100	132	-2248.3	440.0
S101	133	-2323.3	440.0
S102	134	-2398.3	440.0
S103	135	-2473.3	440.0
S104	136	-2548.3	440.0
S105	137	-2623.3	440.0
S106	138	-2698.3	440.0
S107	139	-2773.3	440.0
S108	140	-2848.3	440.0
S109	141	-2923.3	440.0
S110	142	-2998.3	440.0
S111	143	-3073.3	440.0
S112	144	-3148.3	440.0
S113	145	-3223.3	440.0
S114	146	-3298.3	440.0
S115	147	-3373.3	440.0
S116	148	-3448.3	440.0
S117	149	-3523.3	440.0

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SYMBOL	PAD	COORDINATES	
		x	y
S118	150	-3598.3	440.0
S119	151	-3673.3	440.0
S120	152	-3748.3	440.0
S121	153	-3823.3	440.0
S122	154	-3898.3	440.0
S123	155	-3973.3	440.0
S124	156	-4048.3	440.0
S125	157	-4123.3	440.0
S126	158	-4198.3	440.0
S127	159	-4273.3	440.0
S128	160	-4348.3	440.0
S129	161	-4423.3	440.0
S130	162	-4498.3	440.0
S131	163	-4573.3	440.0
S132	164	-4648.3	440.0
S133	165	-4723.3	440.0
S134	166	-4798.3	440.0
S135	167	-4873.3	440.0
S136	168	-4948.3	440.0
S137	169	-5023.3	440.0
S138	170	-5098.3	440.0
S139	171	-5173.3	440.0
S140	172	-5248.3	440.0
COM1_2	173	-5323.3	440.0
COM2_2	174	-5398.3	440.0
Alignment marks			
TARGET1	-	-5645.0	-440.0
TARGET2	-	5645.0	-440.0
Dummy pads			
Dummy1	-	-5644.4	458.4
Dummy2	-	5644.4	458.4
Dummy3	-	-4102.7	-439.4
Dummy4	-	-4027.7	-439.4
Dummy5	-	-3952.7	-439.4
Dummy6	-	-3877.7	-439.4
Dummy7	-	-3802.7	-439.4
Dummy8	-	-3727.7	-439.4
Dummy9	-	-3652.7	-439.4
Dummy10	-	-3577.7	-439.4

SYMBOL	PAD	COORDINATES	
		x	y
Dummy11	-	-3502.7	-439.4
Dummy12	-	-3427.7	-439.4
Dummy13	-	-3352.7	-439.4
Dummy14	-	-3277.7	-439.4
Dummy15	-	-3202.7	-439.4
Dummy16	-	-3127.7	-439.4
Dummy17	-	-3052.7	-439.4
Dummy18	-	-2977.7	-439.4
Dummy19	-	-2902.7	-439.4
Dummy20	-	-2827.7	-439.4
Dummy21	-	-2752.7	-439.4
Dummy22	-	-2677.7	-439.4
Dummy23	-	-2602.7	-439.4
Dummy24	-	-2527.7	-439.4
Dummy25	-	-2452.7	-439.4
Dummy26	-	-2377.7	-439.4
Dummy27	-	-2302.7	-439.4
Dummy28	-	-2227.7	-439.4
Dummy29	-	-2152.7	-439.4
Dummy30	-	-2077.7	-439.4
Dummy31	-	-2002.7	-439.4
Dummy32	-	-1927.7	-439.4
Dummy33	-	-1852.7	-439.4
Dummy34	-	-1777.7	-439.4
Dummy35	-	-1702.7	-439.4
Dummy36	-	-1627.7	-439.4
Dummy37	-	-1552.7	-439.4
Dummy38	-	-327.4	-439.4
Dummy39	-	140.9	-439.4
Dummy40	-	215.9	-439.4
Dummy41	-	290.9	-439.4
Dummy42	-	1231.0	-439.4
Dummy43	-	1306.0	-439.4
Dummy44	-	1381.0	-439.4
Dummy45	-	1456.0	-439.4
Dummy46	-	1531.0	-439.4
Dummy47	-	1606.0	-439.4
Dummy48	-	1681.0	-439.4
Dummy49	-	1756.0	-439.4

LCD driver for 140 × 2 segments

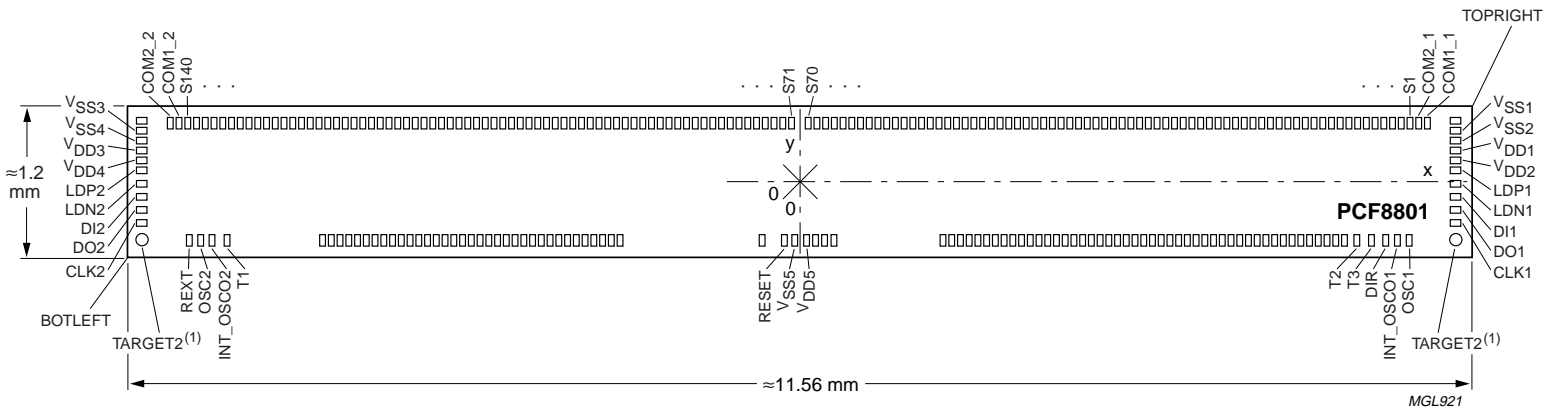
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SYMBOL	PAD	COORDINATES	
		x	y
Dummy50	–	1831.0	–439.4
Dummy51	–	1906.0	–439.4
Dummy52	–	1981.0	–439.4
Dummy53	–	2056.0	–439.4
Dummy54	–	2131.0	–439.4
Dummy55	–	2206.0	–439.4
Dummy56	–	2281.0	–439.4
Dummy57	–	2356.0	–439.4
Dummy58	–	2431.0	–439.4
Dummy59	–	2506.0	–439.4
Dummy60	–	2581.0	–439.4
Dummy61	–	2656.0	–439.4
Dummy62	–	2731.0	–439.4
Dummy63	–	2806.0	–439.4
Dummy64	–	2881.0	–439.4
Dummy65	–	2956.0	–439.4
Dummy66	–	3031.0	–439.4
Dummy67	–	3106.0	–439.4
Dummy68	–	3181.0	–439.4
Dummy69	–	3256.0	–439.4
Dummy70	–	3331.0	–439.4
Dummy71	–	3406.0	–439.4

SYMBOL	PAD	COORDINATES	
		x	y
Dummy72	–	3481.0	–439.4
Dummy73	–	3556.0	–439.4
Dummy74	–	3631.0	–439.4
Dummy75	–	3706.0	–439.4
Dummy76	–	3781.0	–439.4
Dummy77	–	3856.0	–439.4
Dummy78	–	3931.0	–439.4
Dummy79	–	4006.0	–439.4
Dummy80	–	4081.0	–439.4
Dummy81	–	4156.0	–439.4
Dummy82	–	4231.0	–439.4
Dummy83	–	4306.0	–439.4
Dummy84	–	4381.0	–439.4
Dummy85	–	4456.0	–439.4
Dummy86	–	4531.0	–439.4
Dummy87	–	4606.0	–439.4
Dummy88	–	4681.0	–439.4
Chip corners (unsawn wafer)			
BOTLEFT	–	–5780.0	–600.0
TOPRIGHT	–	5780.0	600.0

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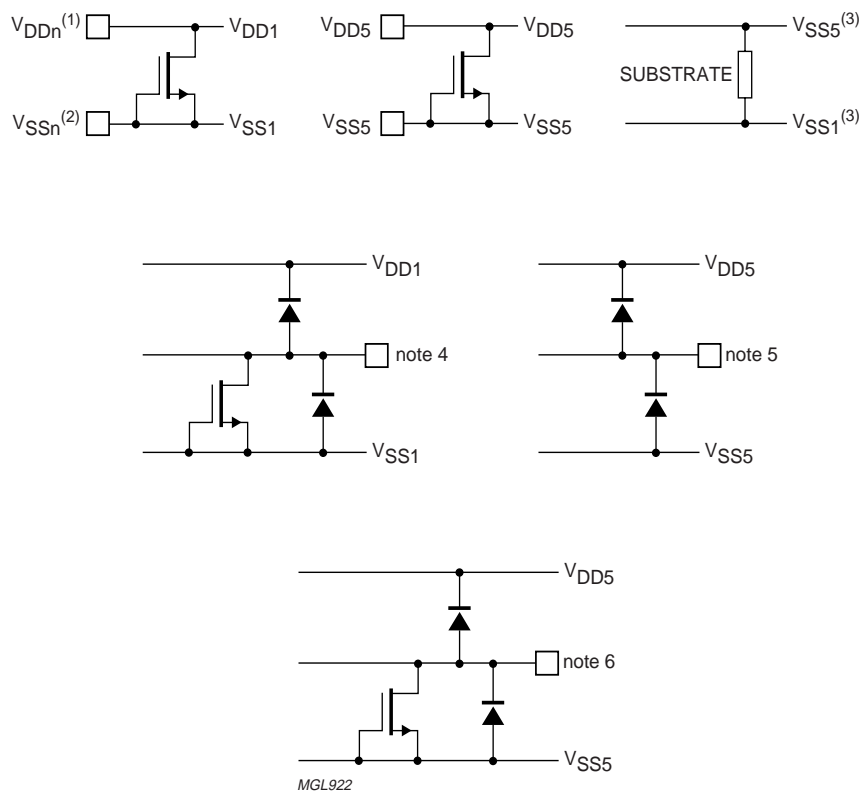


(1) Pattern recognition mark is metal circle of diameter 100 μm.

Fig.6 Bonding pad locations.

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- (1) Pads VDD1 to VDD4; internally linked by metal connections.
- (2) Pads VSS1 to VSS4; internally linked by metal connections.
- (3) VSS1 and VSS5 are internally linked by the substrate resistance.
- (4) Pads COM1, COM2, S1 to S140.
- (5) Pads CLKI, OSCI, LDPI, LDNI, INT_OSCO, CLKO, OSCO, LDPO, LDNO, DO, T2.
- (6) Pads REXT, DIR, RESET, DI, T1, T3.

Fig.7 Device protection diagram.

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TRAY INFORMATION

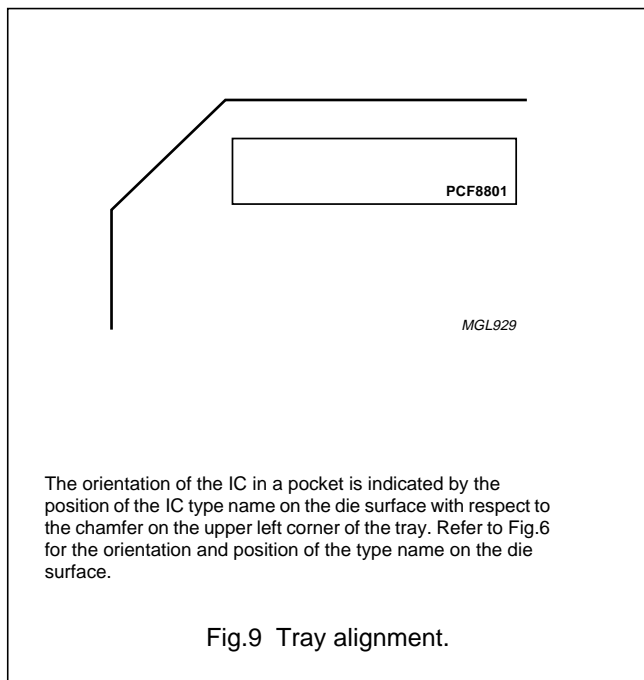
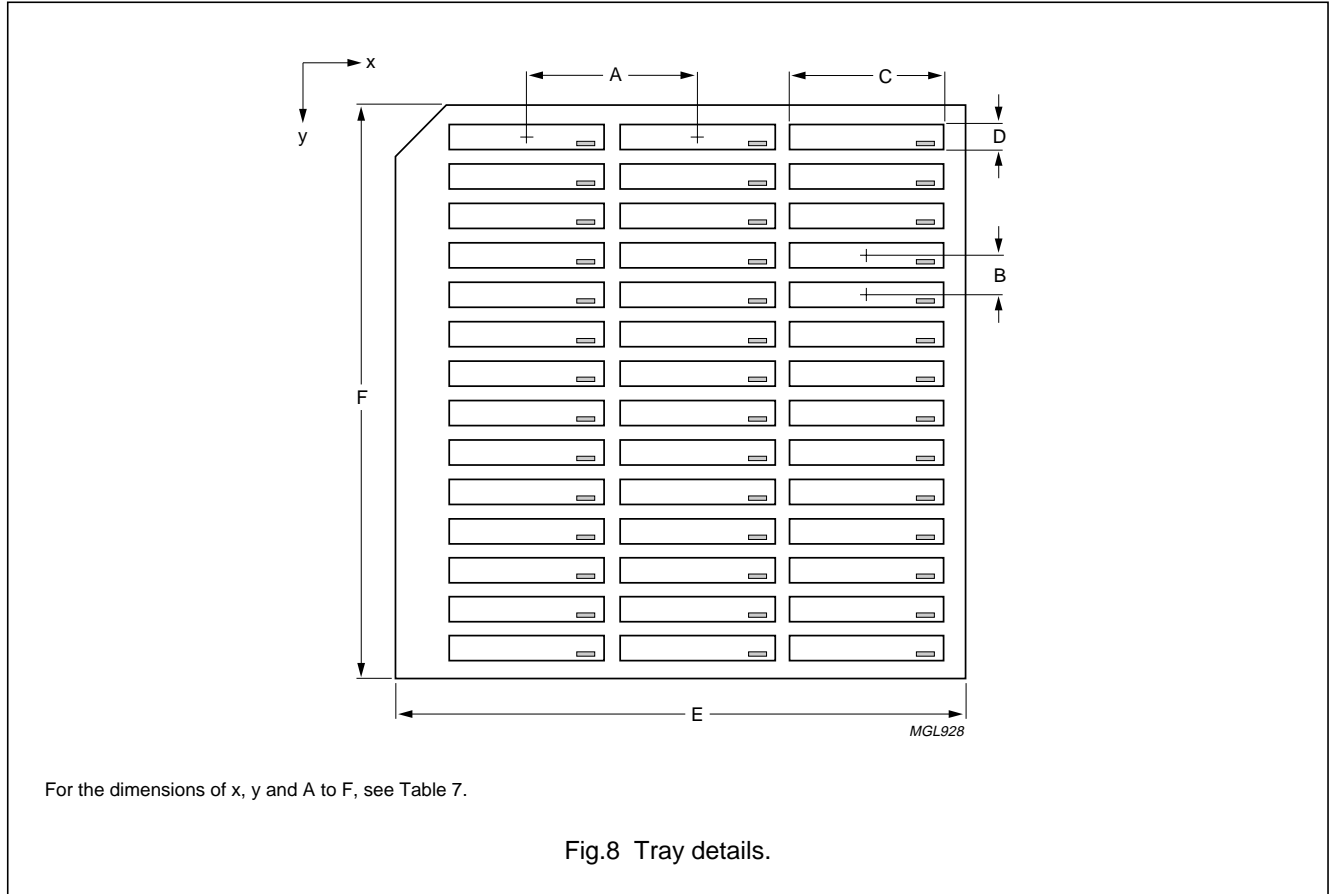


Table 6 Bonding pad dimensions

Pad pitch	min. 75 μm
Pad size, aluminium	62 × 100 μm
Bump dimensions	50 × 90 × 17.5 (±5) μm
Wafer thickness	approx. 380 μm

Table 7 Tray dimensions

DIM.	DESCRIPTION	VALUE
A	pocket pitch, in the x direction	13.97 mm
B	pocket pitch, in the y direction	3.20 mm
C	pocket width, in the x direction	11.66 mm
D	pocket width, in the y direction	1.30 mm
E	tray width, in the x direction	50.80 mm
F	tray width, in the y direction	50.80 mm
x	no. pockets in the x direction	3
y	no. pockets in the y direction	14

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
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